

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	6569	solder same encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 15:04
L4	209	(solder adj joint) same encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 16:22
L6	1	encapsulated adj solder adj joint	IBM_TDB	OR	OFF	2005/06/04 15:30
L7	179	(solder adj connection) same encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 16:22

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L17	189335	epoxy adj resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:13
L18	324224	flux\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:13
L19	1008	17 same 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:14
L21	17	fluxing adj capabilities	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:23
L23	395	epoxy near5 flux\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:44
L24	0	cyclohexyldiepoxy near5 flux\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:29
L25	6	cyclohexyldiepoxy	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:29
L26	0	18 same 25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:29
L27	0	fp0045 near5 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:30
L28	1488	hysol	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:30

L29	0	18 near5 28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/06/04 20:30
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